



IRW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Application of:

Tai-Chun Huang

Group Art Unit: 2891

Serial No.: 10/731,983

Examiner: David A. Zarneke

Filed: Dec. 10, 2003

In Response to Office Action
Dated: June 7, 2005

For: Structure and Method for Reinforcing a Bond Pad on a Chip

Attorney Docket No.: 67,200-1147

Certificate of Mailing

I hereby certify that this paper is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

R. TUNG

7/5/05

RESPONSE TO OFFICE ACTION

Commissioner for Patents
Alexandria, VA 22313-1450

Dear Sir:

In response to an Office Action mailed June 7, 2005 of a restriction requirement imposed by the Examiner, the Applicants hereby elect with traverse the prosecution of Species 1, Figure 5, claims 1-4, 9-11, 13-15 and 17-19.